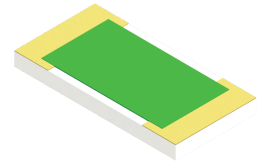


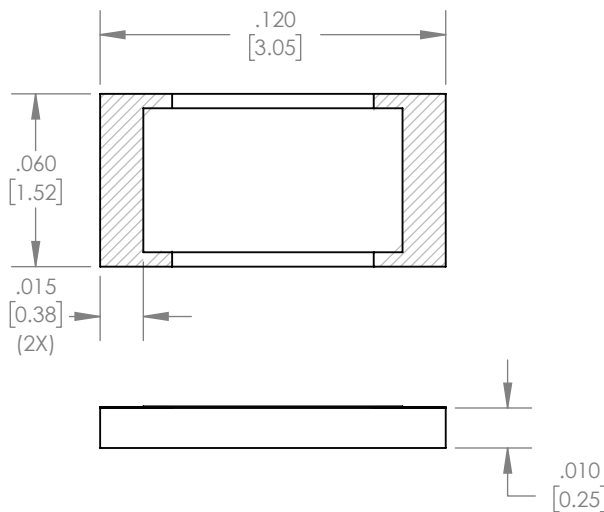
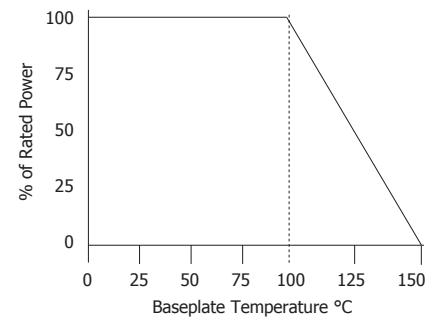
**RS1206ZZ-XXXXWN-95 Features:**

- Single-Sided (Flip-Chip) Terminal Configuration
- Solder, Epoxy or Wirebondable Terminals
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel (Film Side Down) and Waffle Pack Available (Standard is bulk)


**RS1206ZZ-XXXXWN-95 Parameters:**

Resistance Range:	0.5Ω - 1MΩ
Rated Power*:	1.5W
Construction:	Thick Film on 0.010" BeO
Operating Temperature:	-55 to +150°C

\* Rating based on ≤100°C constant baseplate temperature

**RS1206ZZ-XXXXWN-95 Dimensions:**

**RS1206ZZ-XXXXWN-95  
Power Derating Curve**


Dimensions in inches [mm]  
 Tolerance is ± 0.005 [0.13]  
 unless otherwise stated

**Ordering Information:**
**Example Part Number: RS1206CT-50R0JN-95**

RS	1206	ZZ	-	XXXX	W	N	-	95	UU
Prefix for Resistor w/ Single-Sided Terminals				Value Code	Tolerance	Normal Inspection Contact factory for additional options		Substrate 95 - 0.010" BeO	Packaging Blank - Bulk WP - Waffle Pack TRD - Tape & Reel
Size 1206				50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ	1002 - 10KΩ 1003 - 100KΩ 1004 - 1MΩ	F - 1% G - 2% J - 5%			
Terminal Metallization				RoHS	Magnetic	Solder	Epoxy	Wirebond	
AS - Tin Lead over Platinum Palladium Gold				No	No	Yes	No	No	
CB - Tin Lead over Nickel over Silver				No	Yes	Yes	No	No	
CC - 100% Matte Tin over Copper over Silver				Yes	No	Yes	No	No	
CT - 100% Matte Tin over Nickel over Silver				Yes	Yes	Yes	No	No	
JA - Gold over Platinum Palladium Gold				Yes	No	No	Yes	Yes	

Barry Industries reserves the right to change part number and/or process without notification.

**RS1206ZZ-XXXXWN-95 Reliability Specifications:**

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +125 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

Barry Industries reserves the right to change part number and/or process without notification.